

5-104895-8 ✓ ACTIVE

AMPMODU | AMPMODU 50/50 Grid

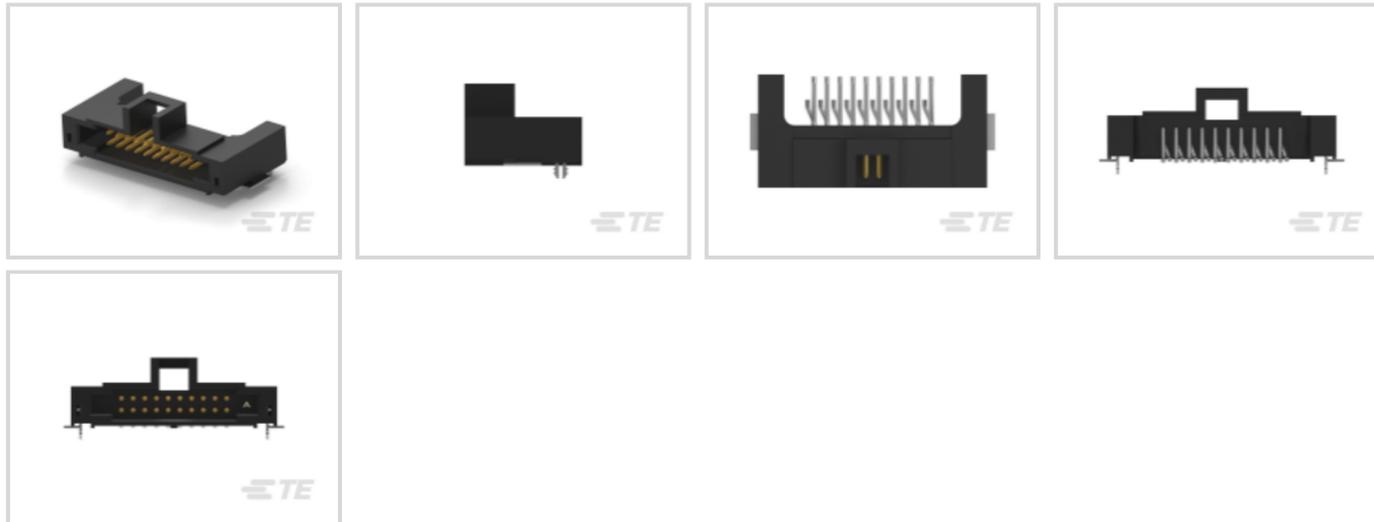
TE Internal #: 5-104895-8

PCB Mount Header, Right Angle, Board-to-Board, 80 Position, 1.27 mm [.05 in] Centerline, Fully Shrouded, Gold, Surface Mount, AMPMODU 50/50 Grid

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: **PCB Mount Header**

PCB Mount Orientation: **Right Angle**

Connector System: **Board-to-Board**

Number of Positions: **80**

Number of Rows: **2**

Features

Product Type Features

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Fully Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Right Angle
Number of Positions	80
Number of Rows	2

Electrical Characteristics

Operating Voltage	30 VAC
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Body Features

Connector Profile	Standard
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Primary Product Color	Black
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Contact Features

	150 µin
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Contact Shape & Form	Square
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Contact Mating Area Plating Material Finish	Bright
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Contact Underplating Material	Nickel
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PCB Contact Termination Area Plating Material	Tin
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Contact Base Material	Brass
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Contact Mating Area Plating Material	Gold
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Contact Type	Pin
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Contact Current Rating (Max)	.5 A
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Termination Features

Termination Method to Printed Circuit Board	Surface Mount
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Mechanical Attachment

Mating Retention	With
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Panel Mount Feature	Without
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PCB Mount Retention Type	Hold-Down Post
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Mating Alignment	With
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Mating Alignment Type	Latched
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PCB Mount Retention	With
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PCB Mount Alignment	With
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Connector Mounting Type	Board Mount
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Housing Features

Centerline (Pitch)	1.27 mm [.05 in]
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Housing Material	LCP (Liquid Crystal Polymer)
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Dimensions

Row-to-Row Spacing	1.27 mm [.05 in]
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Usage Conditions

Operating Temperature Range	-65 – 105 °C [-85 – 221 °F]
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Operation/Application

Solder Process Feature	Board Standoff
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Circuit Application	Power & Signal
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Industry Standards

Approved Standards	CSA LR7189, UL E28476
UL Flammability Rating	UL 94V-0

Packaging Features

Packaging Quantity	8
Packaging Type	Box, Tube

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

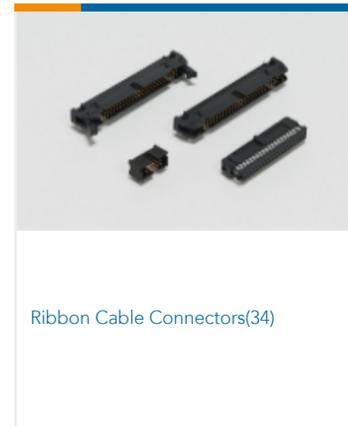
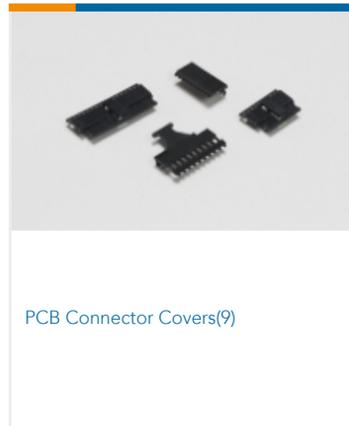
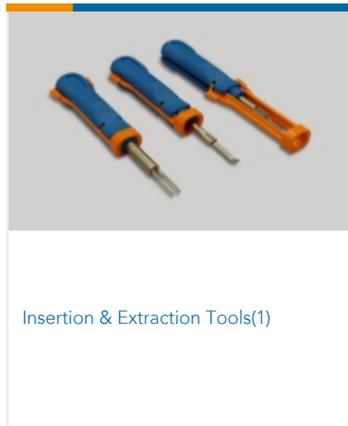
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Also in the Series | AMPMODU 50/50 Grid



Documents

CAD Files

3D PDF

English

Customer View Model

[ENG_CVM_5-104895-8_H.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_5-104895-8_H.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_5-104895-8_H.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

[AMPMODU_INTERCONNECTION_SYSTEM_SECTION1AND2](#)

English

[Ribbon Cable Interconnect Solutions](#)

English

[Fine Pitch Stacking Connectors - 1.27mm AMPMODU 50/50 Grid Connectors](#)

English

Product Specifications

[Application Specification](#)



English

Product Environmental Compliance

TE Material Declaration

English

Agency Approvals

UL Report

English